

# BRCS2305MAQ

Rev.A Feb.-2025

## 描述 / Descriptions

SOT-23 塑封封装 P 道 MOS 场效应管。

P- CHANNEL MOSFET in a SOT-23 Plastic Package.

## 特征 / Features

沟槽功率 MOSFET 技术，低导通电阻，低栅极电荷，符合 AEC-Q101 标准高可靠性要求，无卤产品。

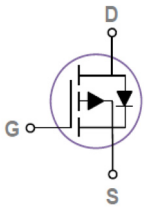
Trench Power MOSFET technology, Low  $R_{DS(ON)}$ , Low Gate Charge, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

## 用途 / Applications

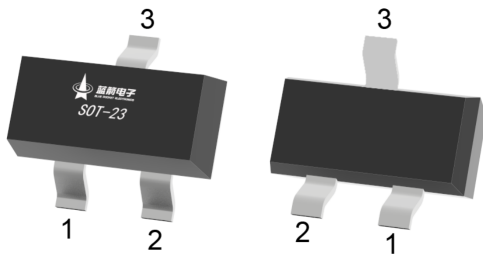
主要用于显示屏驱动，满足汽车应用的严格要求。

Primarily the display screen drive applications, Meet the stringent requirements of automotive applications.

## 内部等效电路 / Equivalent Circuit



## 引脚排列 / Pinning



PIN1 : G

PIN 2 : S

PIN 3 : D

## 印章代码 / Marking

Marking	Q305
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**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current – Continuous	I <sub>D</sub> (T <sub>C</sub> =25°C)	-4.3	A
Pulsed Drain Current	I <sub>DM</sub>	-18	A
Power Dissipation	P <sub>D</sub>	1.3	W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C
Junction-to-Ambient	t ≤ 10	90	°C/W
Junction-to-Ambient	Steady-State	125	
Junction-to-Lead	Steady-State	80	

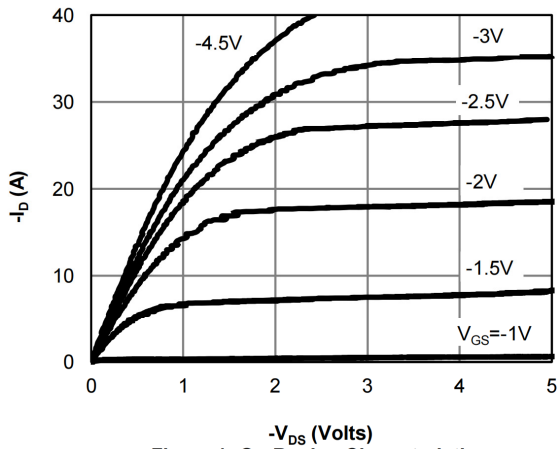
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain–Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-20	-23		V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250μA	-0.4	0.75	-1.0	V
Static Drain–Source On–Resistance	R <sub>DS(on)1</sub>	V <sub>GS</sub> =-4.5V I <sub>D</sub> =-4.3A		33	40	mΩ
	R <sub>DS(on)2</sub>	V <sub>GS</sub> =-2.5V I <sub>D</sub> =-3.0A		45	60	mΩ
	R <sub>DS(on)3</sub>	V <sub>GS</sub> =-1.8V I <sub>D</sub> =-2.0A		63	85	mΩ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V V <sub>GS</sub> =0V			1	μA
Gate–Body Leakage.	I <sub>GSS</sub>	V <sub>GS</sub> =±12V V <sub>DS</sub> =0V			±0.1	μA
Drain–Source Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-1A V <sub>GS</sub> =0V			-1.2	V
Gate Resistance	R <sub>g</sub>			22		Ω
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-5V V <sub>GS</sub> =0V f=1.0MHz		450		pF
Output Capacitance	C <sub>oss</sub>			220		
Reverse Transfer Capacitance	C <sub>rss</sub>			90		
Total Gate Charge	Q <sub>g(4.5V)</sub>	V <sub>GS</sub> =-4.5V V <sub>DS</sub> =-10V I <sub>D</sub> =-4.3A		8.8		nC
Gate Source Charge	Q <sub>gs</sub>			1.2		
Gate Drain Charge	Q <sub>gd</sub>			2.5		

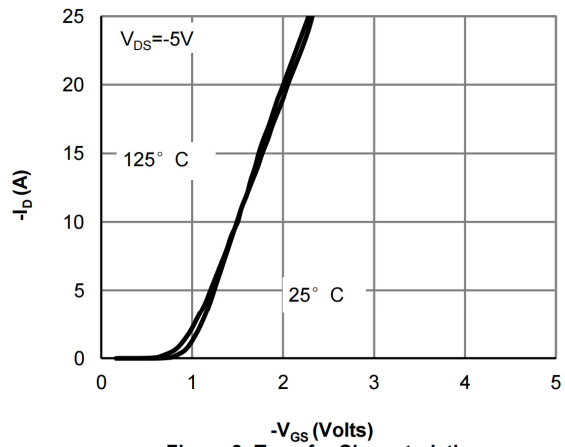
## 电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-4.5V$ $V_{DS}=-10V$ $R_L=2.22\Omega$ $R_{GEN}=3\Omega$		12		ns
Turn-On Rise Time	$t_r$			11.3		
Turn-Off Delay Time	$t_{d(off)}$			80		
Turn-Off Fall Time	$t_f$			32		

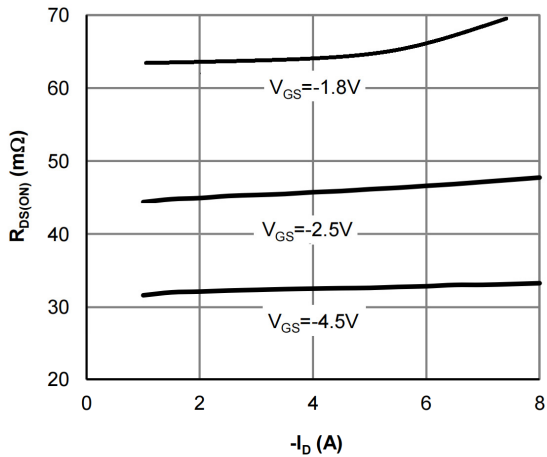
**电参数曲线图 / Electrical Characteristic Curve**



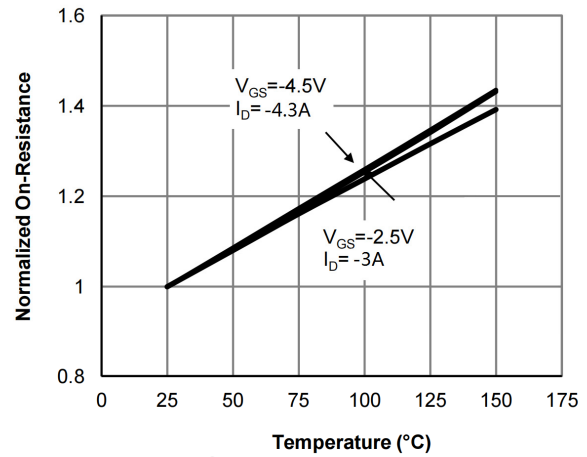
**Figure 1: On-Region Characteristics**



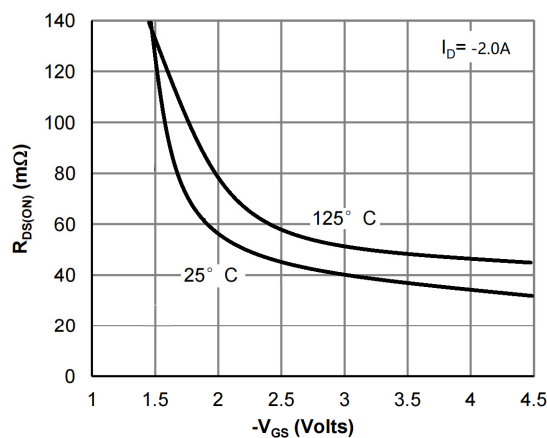
**Figure 2: Transfer Characteristics**



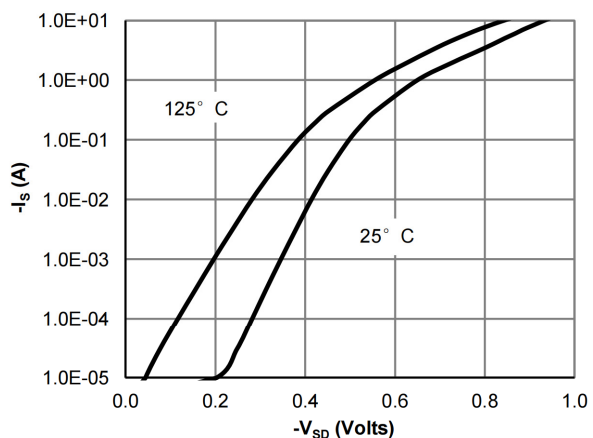
**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**



**Figure 4: On-Resistance vs. Junction Temperature**



**Figure 5: On-Resistance vs. Gate-Source Voltage**



**Figure 6: Body-Diode Characteristics**

## 电参数曲线图 / Electrical Characteristic Curve

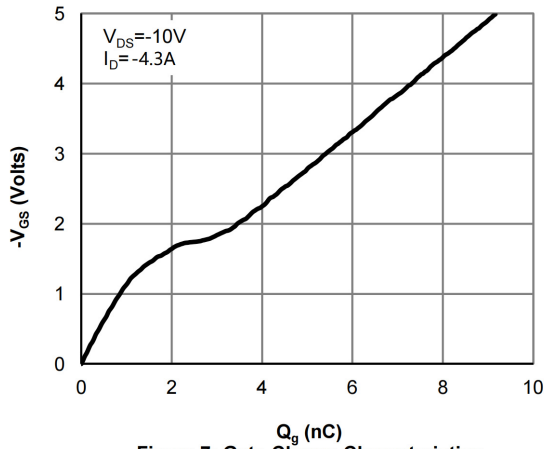


Figure 7: Gate-Charge Characteristics

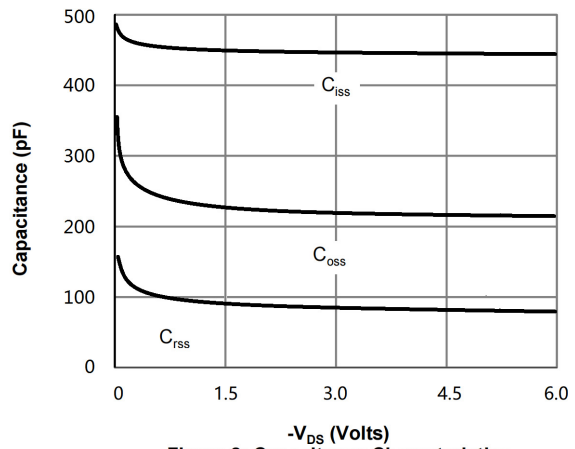


Figure 8: Capacitance Characteristics

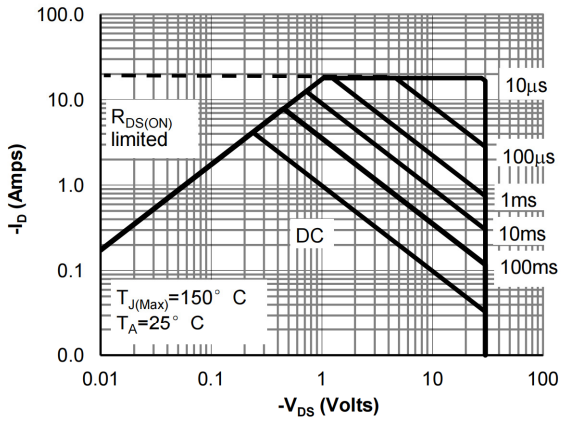


Figure 9: Maximum Forward Biased Safe Operating Area  
 $V_{GS}$  > or equal to -1.8V

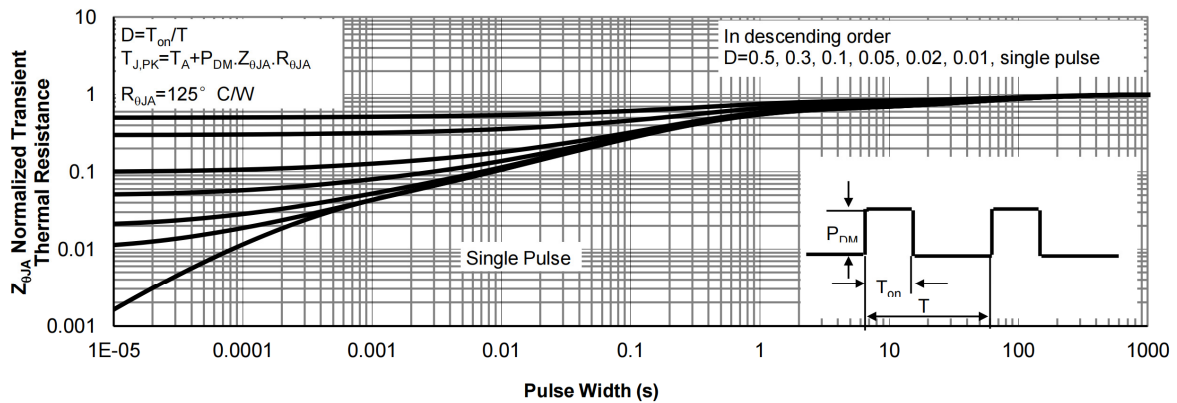
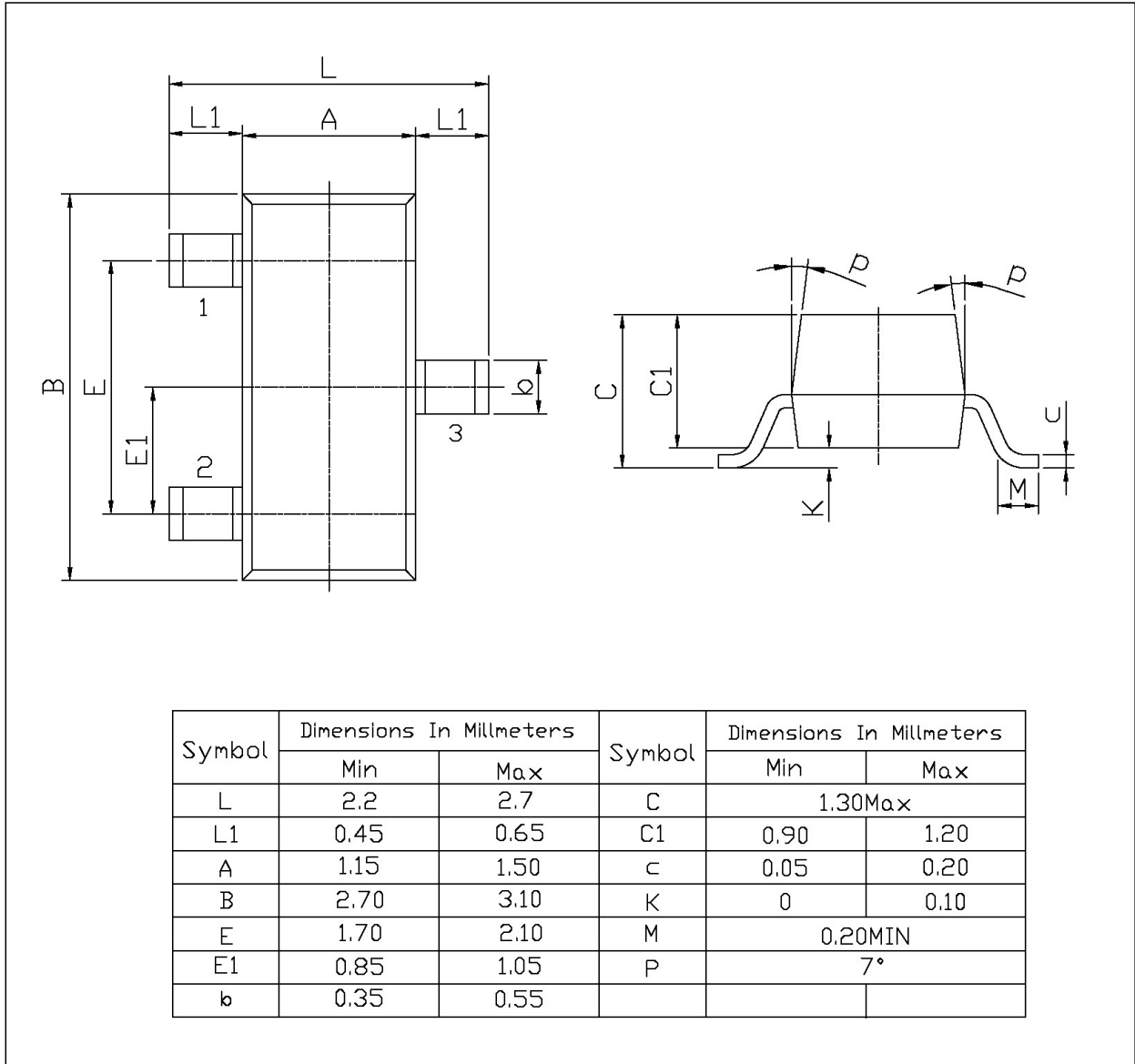


Figure 10: Normalized Maximum Transient Thermal Impedance

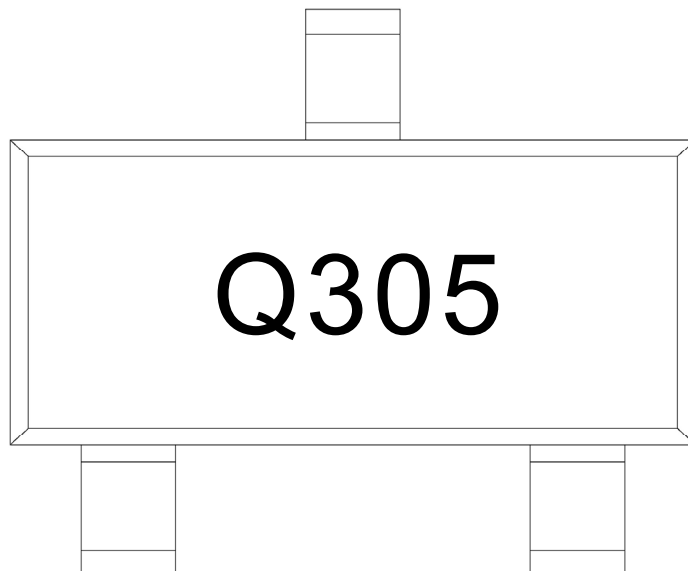
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



**印章说明 / Marking Instructions**



说明：

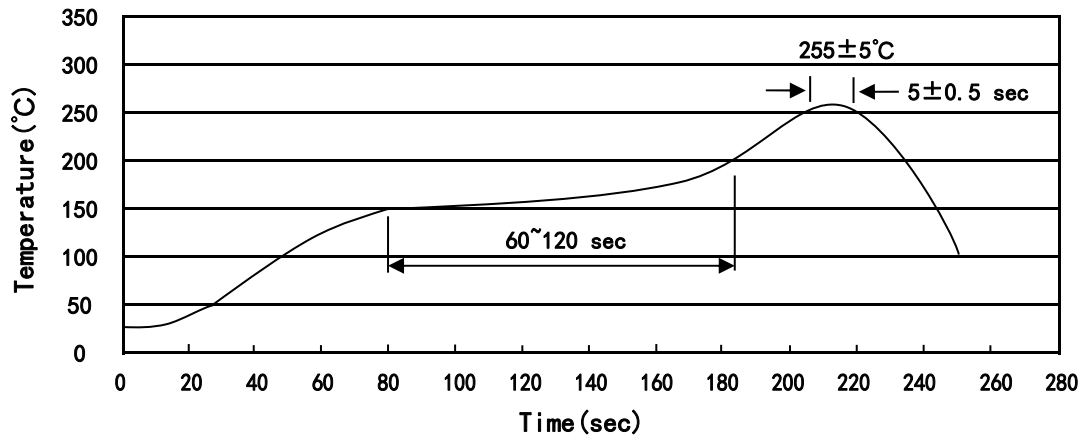
Q： 为汽车无卤产品标识

305： 为型号代码

Note:

Q: Automobile halogen-free product Code

305 : Product Type Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**


说明：

- 1、预热温度 150~200°C，时间 60~120sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~200°C, Time:60~120sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	4	120,000	7" ×8	210×205×205	445×435×230

**使用说明 / Notices**